IN THE CLAIMS

Please amend the claims as follows:

1. (Previously Presented): A transfer mechanism for transferring substrates to be processed with respect to a processing apparatus in a semiconductor processing system, the transfer mechanism comprising:

a transfer base;

a support for supporting the transfer base; and

a first and a second support arm disposed on the transfer base,

wherein the support includes a stretchable and bendable arm that is stretchable and bendable,

wherein the first and the second support arm respectively have a first and a second support surface for holding the substrates to be processed, the first and the second support surface are positioned on a substantially same plane, and the first and the second support arm are operated such that the first and the second support surface are projected from the transfer base toward a substantially equivalent side, and

wherein a first and a second driving motor for respectively sliding the first and the second support arm and a third driving motor for revolving the transfer base are disposed at an outside of the transfer base, and an axis for revolving the transfer base with respect to the support has a three-axis coaxial structure for transferring driving forces of the first to the third driving motors.

2-9. (Canceled)

10. (Previously Presented): The transfer mechanism of claim 1, wherein the first and the second support surface slide along substantially circular arcs, and the first and the second

support surface occupy a same position without having the transfer base revolved or translated when being in a state projected from the transfer base.

11. (Previously Presented): The transfer mechanism of claim 1, wherein the first and the second support surface slide along directions converging toward each other when projected from the transfer base.

12. (Previously Presented): The transfer mechanism of claim 1, wherein the first and the second support surface slide along directions converging toward each other when projected from the transfer base, and the first and the second support surface occupy a same position without having the transfer base revolved or translated when being in a state projected from the transfer base.

13. (Previously Presented): The transfer mechanism of claim 1, wherein the first and the second support surface slide along directions diverging from each other when projected from the transfer base.

14-16. (Canceled)

17. (Previously Presented): A semiconductor processing system comprising:

a common transfer chamber;

a plurality of processing apparatuses connected in parallel to the common transfer chamber; and

a transfer mechanism, disposed in the common transfer chamber, for transferring substrates to be processed relative to the processing apparatuses,

wherein the transfer mechanism includes:

a transfer base; a support for supporting the transfer base; and

a first and a second support arm disposed on the transfer base

wherein the support includes a stretchable and bendable arm that is stretchable and bendable,

wherein the first and the second support arm respectively have a first and a second support surface for holding the substrates to be processed, the first and the second support surface are positioned on a substantially same plane, and the first and the second support arm are operated such that the first and the second support surface are projected from the transfer base toward a substantially equivalent side, and

wherein a first and a second driving motor for respectively sliding the first and the second support arm and a third driving motor for revolving the transfer base are disposed at an outside of the transfer base, and an axis for revolving the transfer base with respect to the support has a three-axis coaxial structure for transferring driving forces of the first to the third driving motors.

18. (Original): The semiconductor processing system of claim 17, further comprising an evacuable load-lock chamber connected in parallel with the processing apparatuses to the common transfer chamber, which is also evacuable.

19. (Previously Presented): The semiconductor processing system of claim 17, wherein the first and the second support surface slide along substantially circular arcs, and the first and the second support surface occupy a same position without having the transfer base revolved or translated when being in a state projected from the transfer base.

20. (Previously Presented): The semiconductor processing system of claim 17, wherein the first and the second support surface slide along directions converging toward each other when projected from the transfer base, and the first and the second support surface occupy a same position without having the transfer base revolved or translated when being in a state projected from the transfer base.

21. (Previously Presented): The semiconductor processing system of claim 17, wherein the first and the second support surface slide along directions diverging from each other when projected from the transfer base.

22. (Canceled)

23. (Previously Presented): The semiconductor processing system of claim 17, further comprising a controller for controlling the transfer mechanism to simultaneously revolve the transfer base and slide at least one of the first and the second support arm.

24. (Previously Presented): The semiconductor processing system of claim 17, wherein the transfer base is linearly movable and the semiconductor processing system further comprising a controller for controlling the transfer mechanism to simultaneously make a linear motion of the transfer base and operate at least one of the first and the second support arm.

25-36. (Canceled)

37. (Previously Presented): The transfer mechanism of claim 1, wherein:

the three-axis coaxial structure has a central axis positioned at a center, an intermediate axis and an outer axis positioned at an outside thereof;

a first and a second bearing are interposed between the central axis and the intermediate axis and between the intermediate axis and the outer axis, respectively; and

the central axis, the intermediate axis and the outer axis are individually rotatable.

38. (Previously Presented): The transfer mechanism of claim 1, further comprising a first and a second guide rail, for respectively guiding the first and the second support surface, each of the first and the second guide rail being formed in a shape of a substantially circular arc,

wherein the first and the second support surface slide along the first and the second guide rail, respectively, and the first and the second support surface occupy a same position when being in a state projected from the transfer base.

39. (Previously Presented): The transfer mechanism of claim 1, further comprising a first and a second guide rail, for respectively guiding the first and the second support surface, each of the first and the second guide rail being formed in a linear shape extending along directions converging toward each other when projected from the transfer base,

wherein the first and the second support surface slide along the first and the second guide rail, respectively, and the first and the second support surface occupy a same position when being in a state projected from the transfer base.

40. (Previously Presented): The transfer mechanism of claim 1, further comprising a first and a second guide rail, for respectively guiding the first and the second support surface,

each of the first and the second guide rail being formed in a linear shape extending along directions diverging from each other when projected from the transfer base

wherein the first and the second support surface slide along the first and the second guide rail, respectively.

41. (Previously Presented): The semiconductor processing system of claim 17, wherein:

the three-axis coaxial structure has a central axis positioned at a center, an intermediate axis and an outer axis positioned at an outside thereof;

a first and a second bearing are interposed between the central axis and the intermediate axis and between the intermediate axis and the outer axis, respectively; and

the central axis, the intermediate axis and the outer axis are individually rotatable.

42. (Previously Presented): The semiconductor processing system of claim 17, wherein the transfer mechanism further includes a first and a second guide rail, for respectively guiding the first and the second support surface, each of the first and the second guide rail being formed in a shape of a substantially circular arc,

wherein the first and the second support surface slide along the first and the second guide rail, respectively, and the first and the second support surface occupy a same position when being in a state projected from the transfer base.

43. (Previously Presented): The semiconductor processing system of claim 17, wherein the transfer mechanism further includes a first and a second guide rail, for respectively guiding the first and the second support surface, each of the first and the second

guide rail being formed in a linear shape extending along directions converging toward each other when projected from the transfer base,

wherein the first and the second support surface slide along the first and the second guide rail, respectively, and the first and the second support surface occupy a same position when being in a state projected from the transfer base.

44. (Previously Presented): The semiconductor processing system of claim 17, wherein the transfer mechanism further includes a first and a second guide rail, for respectively guiding the first and the second support surface, each of the first and the second guide rail being formed in a linear shape extending along directions diverging from each other when projected from the transfer base

wherein the first and the second support surface slide along the first and the second guide rail, respectively.

45. (New): The transfer mechanism of claim 1, wherein the three-axis coaxial structure comprises a central axis and two surrounding axes.

46. (New): The semiconductor processing system of claim 17, wherein the three-axis coaxial structure comprises a central axis and two surrounding axes.